

## R E M A R K S

Claims 1, 2, 4, 6, 7 and 10-14 currently remain in the application. Claims 3, 5, 8 and 9 have been withdrawn as non-elected claims. Claim 1 was earlier amended. Claims 10-14 are newly added claims.

Claims 1, 2, 4, 6 and 7 were rejected under 35 U.S.C. 103 over Matsui in view of Tate. Applicant's argument regarding these references is essentially the same as presented in Amendment "H" which was filed earlier. In the aforementioned Advisory Action, the Examiner referred applicant to Fig. 5a of Matsui, stating that applicant's argument was allegedly based on the interpretation that Matsui did not teach forming an anisotropic conductive layer on the target surface so as to span terminal-forming areas. The Examiner is respectfully requested to note that it was not the basis of applicant's argument. Applicant's argument, instead, was that Matsui did not disclose an anisotropic conductive layer spanning a plurality of terminal-forming areas (each including at least one terminal part and each supporting thereon a corresponding one of a plurality of electronic components). Fig. 5a of Matsui shows only one LSI chip 1 (as an example of "electronic component" as used in claim 1 herein). The idea of mounting a plurality of components is nowhere manifest in Matsui, much less the idea of mounting many components of different sizes or that of preparing terminal-forming areas of different sizes accordingly. Neither does the secondary reference of Tate disclose or even hint at such ideas. It is therefore to be concluded that these two references, even if considered in combination, cannot predicate the Examiner's rejection.

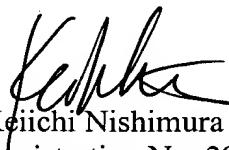
It is further to be noted that the bumps 51 of Matsui (considered by the Examiner as equivalents of the terminal parts of claim 1 herein) are distributed uniformly at equal intervals to support the single electronic component (the LSI chip 1). According to the present invention, as can be seen in Fig. 1, the terminal parts 30a, 30b, 30c are not evenly spaced or uniformly distributed on the surface 10 of the printed circuit board 1. Their spacing is variable, depending on the size of the terminal-forming areas (or that of the electronic component to be mounted thereon). The idea of so varying the spacing the terminal parts is not disclosed or even hinted at in the cited references. Thus, a set of new claims 10-14 is herein added, including the limitation that "the terminal parts are distributed in a non-uniform manner depending on the sizes of said terminal-forming areas". This additional limitation is

intended to further distinguish the present invention from the cited references.

In order to support the set of these newly added claims, a portion of the specification has been amended by inserting a new paragraph. The description in this newly added paragraph is merely for the purpose of verbally explaining what is already disclosed in Fig. 1, or for directing the attention of the reader to a particular feature that existed in Fig. 1 as originally filed. In other words, the newly added paragraph does not introduce any new matter and hence should be deemed enterable.

In summary, it is believed that the instant Amendment is more than responsive to the Final Office Action and the Advisory Action and hence that the Examiner will agree that the application has been allowable and that it is now more so. Such an action at an early date is earnestly solicited.

Respectfully submitted,

  
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